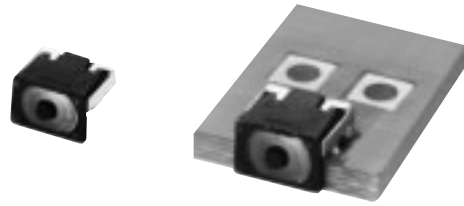## 2.8 mm×2.3 mm Side-operational Edge Mount
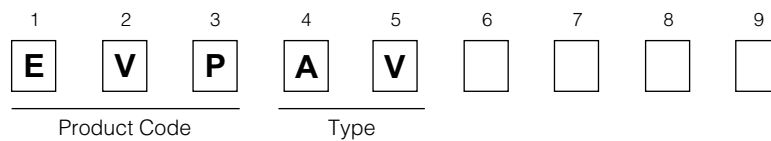## Light Touch Switches
Type: **EVPAV**

■ Features
● External dimensions : 2.8 mm×2.3 mm (Excluding the push plate), Height 1.95 mm (Printed circuit board being as low as 0.975 mm)
● Improved soldering strength in the operating direction

■ Recommended Applications
● Operation switches for portable electronic equipment (Mobile phones, Digital still cameras, Camcorders Portable audio players, etc.)

■ Explanation of Part Numbers

1	2	3	4	5	6	7	8	9
E	V	P	A	V				

Product Code   Type

■ Specifications

Type		Snap action / Push-on type SPST
Electrical	Rating	10 µA 2 Vdc to 20 mA 15 Vdc (Resistive load)
	Contact Resistance	500 mΩ max.
	Insulation Resistance	50 MΩ min. (at 100 Vdc)
	Dielectric Withstanding Voltage	250 Vac (1 minute)
	Bouncing	10 ms max. (ON, OFF)
Mechanical	Operating Force	1.6 N
	Push Travel	0.13 mm
	Push Strength	50 N (15 seconds)
Endurance	Operating Life	300000 cycles min.
Operating Temperature		−40 °C to +85 °C
Storage Temperature		−40 °C to +85 °C (Bulk)
		−20 °C to +60 °C (Taping)
Minimum Quantity/Packing Unit		8000 pcs. Embossed Taping (Reel Pack)
Quantity/Carton		40000 pcs.

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■ Dimensions in mm (not to scale)

EVPAV

General dimension tolerance : ± 0.1
( )dimensions are reference dimensions.
This reference specifications are subject to change.

Circuit Diagram

This product is designed to be smaller than the conventional type, which lowered the film peel off strength. Therefore please avoid to apply force to a push plate from side, or/and avoid set-knob to touch push plate during insertion to a set-case.

2.8
1.95
(φ0.75) Adhesive
φ0.6 Push plate
(1.63)
※2) 1.00±0.08
※2) 1.00±0.08

※1) 0.975±0.200
0.9
2.3±0.2
0.975±0.200
2.00±0.15
0.65±0.15

※1 These dimensions are from the outer shape to the center of push plate.
※2 These dimensions are from the center of datum A.

※1)1.4±0.2
1.93±0.15
0.3
0.65
0.65
(0.98)
(1.88)
(2.8)

3.20±0.05
0.92±0.05
1.50±0.05
0.65±0.05
0.40±0.05
0.45±0.05
1.42±0.05
Push plate side

PWB land pattern for reference

Soldering thickness t=0.1±0.02

※ Height from surface of PCB : 0.975 mm

■ Recommended Reflow Soldering Conditions

MAX.
260
230
180
150
Operation Top (°C)
Fan or Normal Temp.
(Normal Temp.)
90±30
40±10
Soldering Time (s)

● Embossed Carrier Taping

Tape width=8.0 mm

φG
Feeding hole
Chip pocket
Tape running direction

Taping condition : Lack of products in the middle of taping should be one MAX, but total quantity specified in the specifications should be secured.
Peeling off strength of top tape : It should be within 0.2N to 1. ON at 165 degree in peeling off angle.
Joint of carrier tape : One joint per one reel may exist.

Unit: mm

Part No.	Height	A	B	C	D	E	F	G	H	I	J	K	L	t
EVPAV	1.95	8.0±0.3	1.75±0.10	3.5±0.1	4.0±0.1	4.0±0.1	2.0±0.1	$1.5^{+0.1}_{0}$	3.1±0.2	2.8±0.2	1.35±0.20	2.7±0.2	(6.25)	0.3±0.1

● Standard Reel Dimensions in mm (not to scale)

Item	A	B	C	D	E
Rate (mm)	φ380.0±2.0	φ80.0±1.0	φ13.0±0.5	φ21.0±1.0	2.0±0.5

Item	F	G
Rate (mm)	9.4±1.0	13.4±1.0

Design and specifications are each subject to change without notice. Ask factory for the current technical specifications before purchase and/or use.
Should a safety concern arise regarding this product, please be sure to contact us immediately.
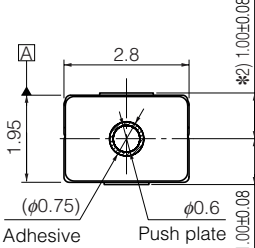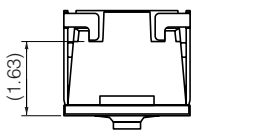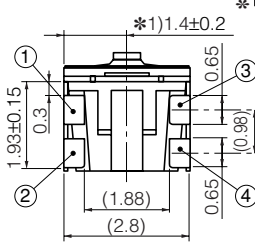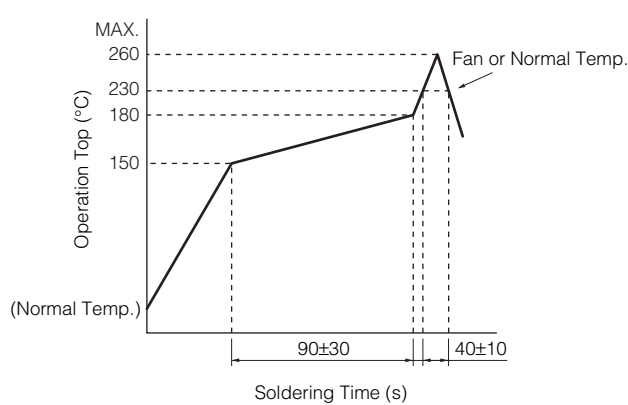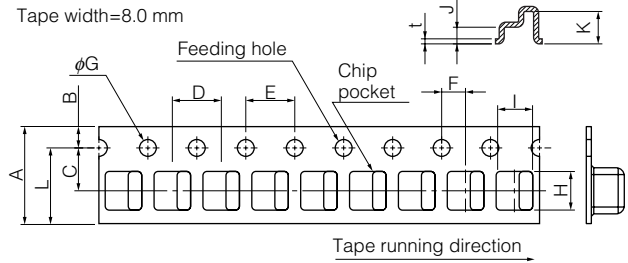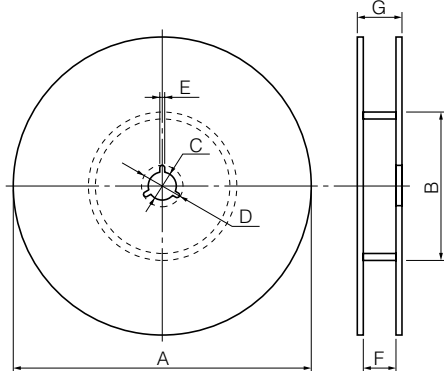
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